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## ABSTRACT OF THE DISCLOSURE

POLYPROPYLENE RESIN COMPOSITION AND  
HEAT-SHRINKABLE FILM OBTAINED FROM THE SAME

Disclosed is a polypropylene resin composition containing from 20 to 99.99 parts by weight of a propylene-based polymer (A) having a die swell ratio of less than 1.7 and a melting point defined as a peak temperature of a peak with a maximum intensity in a melting curve measured by DSC of from 125 to 139°C, and from 0.01 to 80 parts by weight of a propylene-based polymer (B) having a die swell ratio of not less than 1.8. This resin composition is suitable as a raw material of a heat-shrinkable film superior in rigidity, heat shrinkage and weld-cut sealability. A heat-shrinkable film obtainable from the resin composition is also disclosed.